

INTERNATIONAL STANDARD



**Semiconductor devices – Micro-electromechanical devices –
Part 38: Test method for adhesion strength of metal powder paste in MEMS
interconnection**

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interconnection**

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CONTENTS

FOREWORD.....	3
1 Scope.....	5
2 Normative references	5
3 Terms and definitions	5
4 Test piece	6
4.1 General.....	6
4.2 Shape of a test piece	6
4.3 Measurement of dimensions	7
4.4 Evaluation of adhesion strength.....	7
5 Testing method and test apparatus.....	8
5.1 Test principle	8
5.2 Test apparatus.....	8
5.3 Test procedure.....	8
5.4 Test environment	9
6 Test report.....	9
Annex A (informative) Examples of adhesion strength measurement for metal powder paste	10
A.1 General.....	10
A.2 Adhesion strength measurement.....	10
Bibliography.....	12
Figure 1 – Circularly patterned test piece for metal powder paste	7
Figure 2 – Schematic of a testing apparatus	9
Figure A.1 – Examples of measured force and contact area.....	10
Figure A.2 – Examples of maximum contact force, contact area, and adhesion strength	11

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DEVICES –
MICRO-ELECTROMECHANICAL DEVICES –

**Part 38: Test method for adhesion strength of
metal powder paste in MEMS interconnection**

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The text of this International Standard is based on the following documents:

FDIS	Report on voting
47F/378/FDIS	47F/382/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

A list of all parts in the IEC 62047 series, published under the general title *Semiconductor devices – Micro-electromechanical devices*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

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SEMICONDUCTOR DEVICES – MICRO-ELECTROMECHANICAL DEVICES –

Part 38: Test method for adhesion strength of metal powder paste in MEMS interconnection

1 Scope

This part of IEC 62047 specifies a test method for measuring the adhesion strength of metal powder paste in the electrical interconnection between micro-electromechanical systems (MEMS) and a circuit board. The typical examples of metal powder paste are anisotropic conductive paste, solder paste, and nanoscale metallic inks. This testing method is valid for metal powder diameters from 10 µm and 500 µm.

In this test method, a uniaxial compression load is applied to metal powder paste using a glass lens simulating an actual MEMS device; then, the adhesion strength is measured by retracting the lens. This test method is proper when the adhesion strength should be analyzed by considering the actual contact area between the MEMS device and metal powder particles.

2 Normative references

There are no normative references in this document.

3 Terms and definitions

For the purposes of this document, the following terms and definitions apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- ISO Online browsing platform: available at <http://www.iso.org/obp>
- IEC Electropedia: available at <http://www.electropedia.org/>

3.1 contact load

P_L
predetermined force when the lens is contacted with metal powder paste

Note 1 to entry: Contact load is expressed in N.

3.2 maximum pulling force

P_C
maximum of pulling force endurable for a test piece

Note 1 to entry: Maximum pulling force is expressed in N.

3.3 contact area only with metal powder

A_{MP}
contact area made with metal powder only when the contact load (P_L) is applied

Note 1 to entry: Contact area only with metal powder is expressed in m².

3.4 contact area with metal powder paste

 A_{MPP}

contact area made with metal powder paste when the contact load (P_L) is applied

Note 1 to entry: Contact area with metal powder paste is expressed in m^2 .

3.5 adhesion strength

 S_C

maximum pulling force (P_C) divided by the contact area

Note 1 to entry: Adhesion strength is expressed in N/m^2 .

3.6 separation speed

 V_{SEP}

predetermined speed when the test pieces are retracted from the lens

Note 1 to entry: Separation speed is expressed in $\mu m/s$.

3.7 contact radius

 a

radius of contact area when the contact area with metal powder paste is assumed to the area of a circle

Note 1 to entry: Contact radius is expressed in m .

3.8 radius of curvature

 R

radius of curvature of the lens, which simulates an actual device

Note 1 to entry: Radius of curvature of the lens is expressed in m .

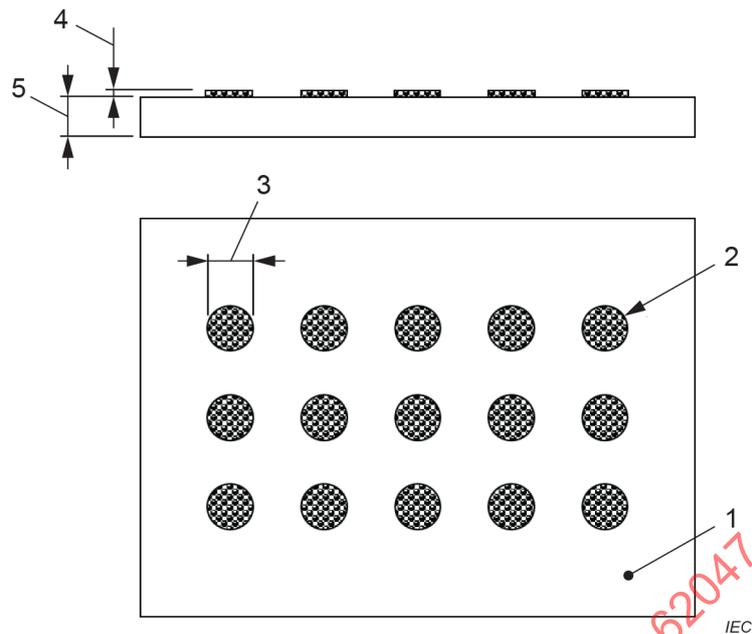
4 Test piece

4.1 General

The test piece for metal powder paste shall be prepared using the same preparation process for MEMS interconnection. The circular patterns of a metal powder paste shown in Figure 1 is formed by screen printing, ink-jet printing, or other deposition techniques. The interface between the metal powder paste and the substrate and the interface between the metal powder paste and the counterpart lens shall be identical to the situation of MEMS interconnection.

4.2 Shape of a test piece

The shape of the test piece and its components are presented in Figure 1. The overall shape of the test piece is similar to a circular disk with a diameter and thickness. Circular disks are formed on a substrate material.

**Key**

- 1 substrate material
- 2 circularly patterned metal powder paste
- 3 diameter of circularly patterned metal powder paste
- 4 thickness of metal powder paste
- 5 thickness of the substrate

Figure 1 – Circularly patterned test piece for metal powder paste

The radius of a test piece shall be at least 50 times smaller than the radius of curvature of lens (R). The thickness of a test piece shall be at least 2 times larger than that of the diameter of a single metal particle. The distance between test pieces shall be large enough to avoid interference during the test.

4.3 Measurement of dimensions

To analyze the test results, the dimensions of the contact area shall be accurately measured because the dimensions are used to determine the adhesion strength of test materials. The contact area between the glass lens and metal powder or metal powder paste should be measured using an optical microscope and image analysis with an error of less than $\pm 5\%$. Information on dimensional measurement can be found in Annex C of IEC 62047-2:2006 and in Clause 6 of IEC 62047-3:2006.

4.4 Evaluation of adhesion strength

The adhesion strength (S) of metal powder paste is evaluated using the following Formula (1):

$$S = P_C / A_{MPP} \quad (1)$$

The adhesion strength (S_C) of metal powder is evaluated using the following Formula (2):

$$S_C = P_C / A_{MP} \quad (2)$$

Here, P_C is the maximum pulling force, A_{MPP} is the contact area between the glass lens and metal powder paste, and A_{MP} the contact area between the glass lens and metal powder.

5 Testing method and test apparatus

5.1 Test principle

The test is performed by applying the contact load on the metal powder paste using a cleaned glass lens with a few millimetre curvature, and then by detaching the lens from the paste to evaluate the adhesion strength of the paste. A test example can be found in Annex A. During the loading process, the metal powder in the paste is deformed by the contact with the lens and the contact area between the lens and the metal powder is formed. The changes in the contact area are recorded by an optical microscope and CCD camera. The contact area is calculated by analyzing the recorded images after the test. During the unloading process, the contact load is decreased and a pulling force is applied on the interface between the lens and the paste due to the adhesion between them. After the maximum pulling force reaches, the contact area is rapidly decreased and the lens is completely separated from the paste. The adhesion strength of the metal powder paste can be evaluated by dividing the maximum pulling force with the contact area between the lens and the metal powder measured before the unloading process. The lens can be coated with thin metal films such as Au and Al for simulating the electrode materials of MEMS.

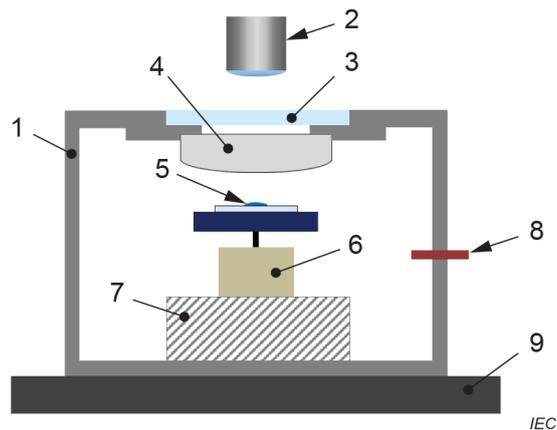
5.2 Test apparatus

The test machine is shown in Figure 2. The glass lens is fixed on the top of the chamber by clamping and the metal powder paste test piece is installed on the sample stage. The test piece is moved toward the glass lens by moving the z-axis motorized stage for the loading process and then is separated from the lens by moving down the z-axis stage for the unloading process. During the test, the force is measured by loadcell, and optical images of the contact area are recorded using an optical microscope and CCD camera. The contact area images shall be recorded at a speed larger than 30 Hz using a camera with a microscope objective of 20x or more.

5.3 Test procedure

The test procedure is as follows:

- a) install a test piece on the sample stage and start to record loadcell output signal and optical microscope images;
- b) apply a contact load to the test piece by moving the Z-axis stage. This is a loading process. The test piece is made contact with the glass lens fixed on the chamber and compressed, so the contact area between the lens and paste is formed;
- c) hold the contact for a holding time of a few seconds. This is for stabilizing the contact interface;
- d) separate the test piece from the lens by moving down the z-axis stage with a separation speed. This is the unloading process;
- e) after testing, remove the test piece from the test machine with caution. If possible, preserve the test piece for investigation using electron and optical microscopes.

**Key**

- 1 chamber
- 2 microscopic camera
- 3 transparent window
- 4 glass lens
- 5 test piece
- 6 load cell
- 7 precision 3-axis stage
- 8 thermo-hygrometer
- 9 anti-vibration table

Figure 2 – Schematic of a testing apparatus

5.4 Test environment

Because the physical properties of metal powder paste are temperature sensitive, fluctuations in temperature during the test shall be controlled to be less than ± 2 °C. The adhesion of the glass lens can be sensitive to humidity; thus, the change in relative humidity (RH) in the testing laboratory shall be controlled to be less than ± 5 % RH for such materials. Because the adhesion test is sensitive to contaminants such as air-borne particles and dust, the test should be conducted in a cleanroom of class 1 000 or 10 000.

6 Test report

The test report shall contain the following information:

- a) reference to this international standard;
- b) test piece identification number;
- c) test piece preparation procedures;
- d) test piece dimensions;
- e) constituent materials and their fabrication methods;
- f) description of the test machine and lens;
- g) description of the test conditions: contact load, holding time, separation speed, humidity, temperature, waiting time after the preparation of the test piece;
- h) measured results and properties: pulling force versus time, adhesion strength versus contact load, images of the contact area, the magnitude of the contact area.

Annex A (informative)

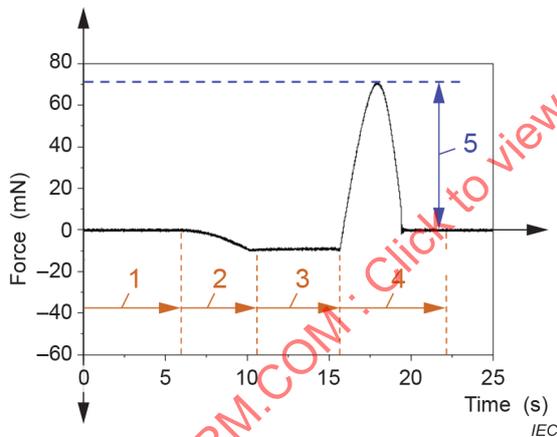
Examples of adhesion strength measurement for metal powder paste

A.1 General

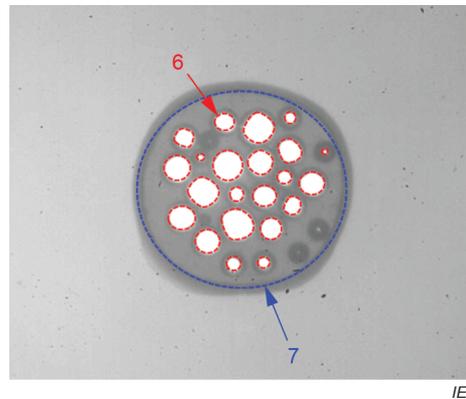
The adhesion between MEMS devices and a metal powder paste plays a critical role in transferring the MEMS devices on the powder paste formed on a circuit board. Adhesion strength changes according to the contact area. The contact area between MEMS devices and a metal powder paste is composed of metallic contact area and resin contact area, and the adhesion strength changes according to the ratio of metallic contact area and resin contact area. For a successful interconnection, the metallic contact area should be dominated over the resin contact area.

A.2 Adhesion strength measurement

During the adhesion strength measurement test, a uniaxial compression load is applied to a metal powder paste using a tool simulating an actual device. From the test, the force applied on metal powder paste (the metal powder is made of SAC305 alloy.) and the contact area between the lens and metal powder paste are measured as shown in Figure A.1. The adhesion strength of metal powder can be calculated from the measured maximum pulling force and the measured contact area only with metal powder as shown in Figure A.2.



a) Measured force during the test



b) Optical microscope image of the contact area

Key

- 1 approach process
- 2 loading process
- 3 holding process
- 4 unloading process
- 5 maximum pulling force
- 6 contact area only with metal powder
- 7 contact area with metal powder paste

Figure A.1 – Examples of measured force and contact area